

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT										
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>JEONG TAE KIM</td> <td>11/20/2008</td> </tr> <tr> <td>SEUNG JIN YEOM</td> <td>11/20/2008</td> </tr> <tr> <td>BAEK MANN KIM</td> <td>11/20/2008</td> </tr> <tr> <td>DONG HA JUNG</td> <td>11/20/2008</td> </tr> </tbody> </table>		Name	Execution Date	JEONG TAE KIM	11/20/2008	SEUNG JIN YEOM	11/20/2008	BAEK MANN KIM	11/20/2008	DONG HA JUNG	11/20/2008
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<b>RECEIVING PARTY DATA</b>											
<b>Name:</b>	HYNIX SEMICONDUCTOR INC.										
<b>Street Address:</b>	San 136-1, Ami-ri, Bubal-eub, Icheon-si										
<b>City:</b>	Kyoungki-do										
<b>State/Country:</b>	KOREA, REPUBLIC OF										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12326374</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12326374						
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Application Number:	12326374										
<b>CORRESPONDENCE DATA</b>											
<b>Fax Number:</b>	(312)427-6663										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
<b>Phone:</b>	3124271300										
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<b>ATTORNEY DOCKET NUMBER:</b>	CU-7062 WWP/NK										
<b>NAME OF SUBMITTER:</b>	Woochoon W. Park										
<b>Total Attachments: 2</b> source=cu7062assign#page1.tif source=cu7062assign#page2.tif											

CH \$40.00 12326374

**PATENT**

UNITED STATES OF AMERICA  
ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNORS:

Name: Jeong Tae KIM

Address: 405-102, Kkachimaeul Seonkyeong Apt., Gumi-dong, Bundang-gu, Seongnam-si, Gyeonggi-do, Korea

Name : Seung Jin YEOM

Address : 206-1601, Hyundai Prime Apt., Pungdeokcheon 2-dong, Suji-gu, Yongin-si, Gyeonggi-do, Korea

Name: Baek Mann KIM

Address: 441-1503, Hyundai Hometown 4-cha 3-danji Apt., Jukjeon 1-dong, Suji-gu, Yongin-si, Gyeonggi-do, Korea

Name: Dong Ha JUNG

Address: 102-201, Seohyun Morningville, 188-18, Seohyun-dong, Bundang-gu, Seongnam-si, Gyeonggi-do, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

ASSIGNEE:

Name : Hynix Semiconductor Inc.

Address : San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:  
METAL LINE OF SEMICONDUCTOR DEVICE AND METHOD FOR FORMING THE SAME

(TITLE)

and which is found in *(check one applicable item below)*

U.S. patent application executed on even date herewith

U.S. Application Serial No. \_\_\_\_\_ filed on \_\_\_\_\_

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

November 20, 2008  
Date

November 20, 2008  
Date

November 20, 2008  
Date

November 20, 2008  
Date

*Kim Jeong Tae*  
INVENTOR: Jeong Tae KIM

*Yeom, Seung Jin*  
INVENTOR: Seung Jin YEOM

*Kim Baek Mann*  
INVENTOR: Baek Mann KIM

*Jung Dong Ha*  
INVENTOR: Dong Ha JUNG

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